

Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

Subject: Addendum to PCN#165004: Introduction of Die Overcoat for Automotive NOR Flash

Memory Products

To: GENERAL INBOX PREMIER FARNELL

ProductChangeNotices@premierfarnell.com

Change Type: Minor

Description of Change:

The purpose of this addendum is to extend the coverage of PCN165004. Refer to attached 'Affected Parts List' file for the complete list of parts affected by the PCN165004.

Cypress has qualified a Die Overcoat process for Automotive NOR Flash Memory products for the 65nm GL-S product family manufactured at Fab 25 in Austin, Texas.

Cypress is adding a polybenzoxazole (PBO) layer on the topside of the wafer. Cypress Fab 4 has successfully utilized a Die Overcoat process on non-Flash product production for over a decade. Cypress is now extending this best practice to Fab 25 on the GL-S Automotive NOR Flash Memory product family.

Benefit of Change:

The Die Overcoat will provide a higher level of protection to the silicon surface during production (Fab, Sort, and Assembly). As a result, it will minimize the risk of latent failures due to surface damage. Functionality and specifications remain unchanged.

Affected Parts: 98

Part Numbers Affected: See the attached 'Affected Parts List' file for the list of part numbers affected by this change. The 'Affected Parts List' includes the customer PPAP Part number (Marketing Part number), the Equivalent Cypress Part number as well as the Sample Order Part number. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

The change has been qualified through a series of tests documented in Qualification Test Plan QTP 162801. This qualification report can be found as an attachment to this notification.

Sample Status:

Samples are available for Sample Order part numbers as indicated in the attached Affected Parts List. Please contact your local sales representative to place any sample requests as soon as possible.

Approximate Implementation Date:

This change will be effective upon customer approval.

Anticipated Impact:

None anticipated. Products manufactured with the new process are completely compatible with existing products from a functional, parametric, and quality performance perspective.

Based on our history and experience, Cypress sees this as a low-risk change to series production. The Die Overcoat process is a very mature process. It is applied on top of the existing passivation layer and has no electrical interaction with the circuit. Cypress is confident that the implementation of this change will not require our customers to perform extensive qualifications.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration